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AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1. (Currently Amended) An integrated circuit device, comprising:
   an active chip of a semiconductor material comprising an electrical circuit, the active chip having an active face provided with a plurality of electrical connection terminals and a second face, wherein the chip has a thickness of less than 100 [[p]]μm, and
   a complementary chip having a first face attached to the active face of the active chip, a second face and a side surface, wherein the complementary chip has a plurality of recesses, each recess extending through the whole thickness of the complementary chip and extending from above a contact terminal to said side surface, the complementary chip having a larger thickness than the active chip, wherein each recess extends laterally inward from a perimeter of the complimentary chip.

2. (Currently Amended) The integrated circuit device of claim 1, wherein the thickness of the active layer ranges from 5 to 50 [[p]]μm.

3. (Currently Amended) The integrated circuit device of claim 2, wherein the thickness of the complementary layer ranges from 100 to 200 [[p]]μm.

4. (Previously Presented) The integrated circuit device according to any of claims 1 to 3, wherein the complementary chip is formed with the same semiconductor material as the active chip.

5. (Currently Amended) An electronic unit for smart cards, comprising:
   an active chip of a semiconductor material comprising an electrical circuit, the active chip having an active face provided with a plurality of electrical connection terminals and a second face, wherein the chip has a thickness of less than 100 [[p]]μm,
   a complementary chip having a first face attached to the active face of the active chip, a second face and a side surface, wherein the complementary chip has a plurality of recesses, each recess extending through the whole thickness of the complementary chip and extending from above a contact terminal to said side surface, the

complementary chip having a larger thickness than the active chip, wherein each recess extends laterally inward from a perimeter of the complimentary chip,

an insulating substrate having an outer face provided with outer electrical contact pads and an inner face, the second face of the active chip being attached to the substrate inner face, and

a plurality of electrical leads, each lead having a first end connected to a contact terminal and a second end connected to an outer contact pad and lying entirely between the plane containing the second face of the complementary chip and the insulating substrate.

6. (Previously Presented) The electronic unit of claim 5, wherein the insulating substrate includes windows, each window being disposed above an outer electric contact pad.

7. (Original) A smart card comprising an electronic unit according to claim 5.

8. (Cancelled)

9. (New) The integrated circuit device of claim 1, wherein surface area of the first face of the complementary chip is substantially the same as surface area of the active face of the active chip.

10. (New) The electronic unit of claim 5, wherein surface area of the first face of the complementary chip is substantially the same as surface area of the active face of the active chip.

11. (New) An integrated circuit device, consisting of:

an active chip of a semiconductor material comprising an electrical circuit, the active chip having an active face comprising a plurality of contact terminals and a second face, wherein the chip has a thickness of less than 100 μm, and

a complementary chip having a first face attached to the active face of the active chip and a second face, wherein the complementary chip has a plurality of recesses, each recess extending through the whole thickness of the complementary chip,

wherein each recess extends laterally inward from a perimeter of the first face of the complimentary chip to a location above one of the plurality of contact terminals.

12. (New) The integrated circuit device of claim 11, wherein surface area of the first face of the complementary chip is substantially the same as surface area of the active face of the active chip.

13. (New) The integrated circuit device of claim 12, wherein the complementary chip has a larger thickness than the active chip.